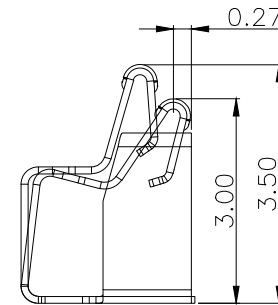
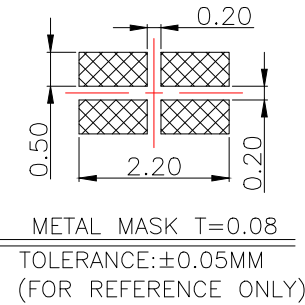
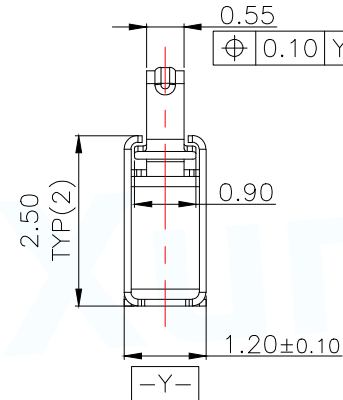
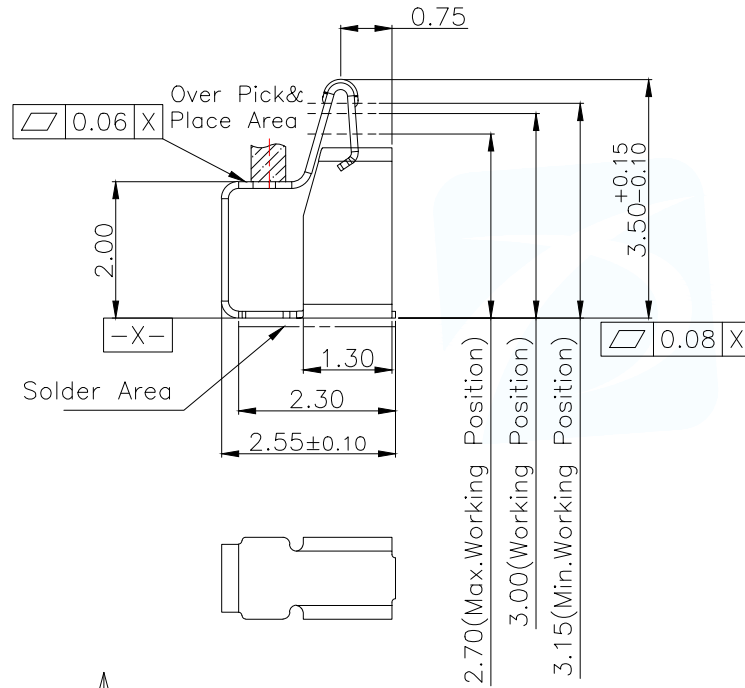


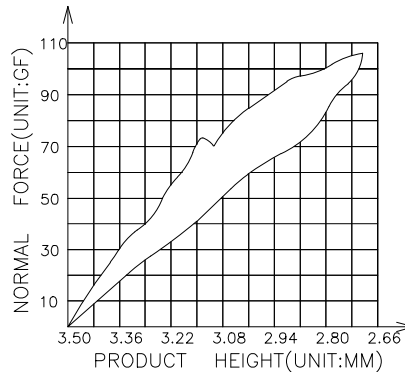
3D View

NOTES:

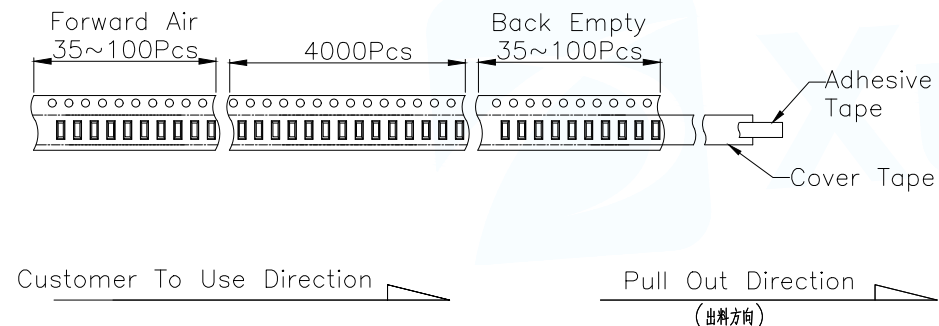
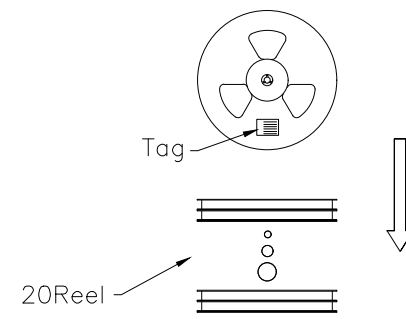
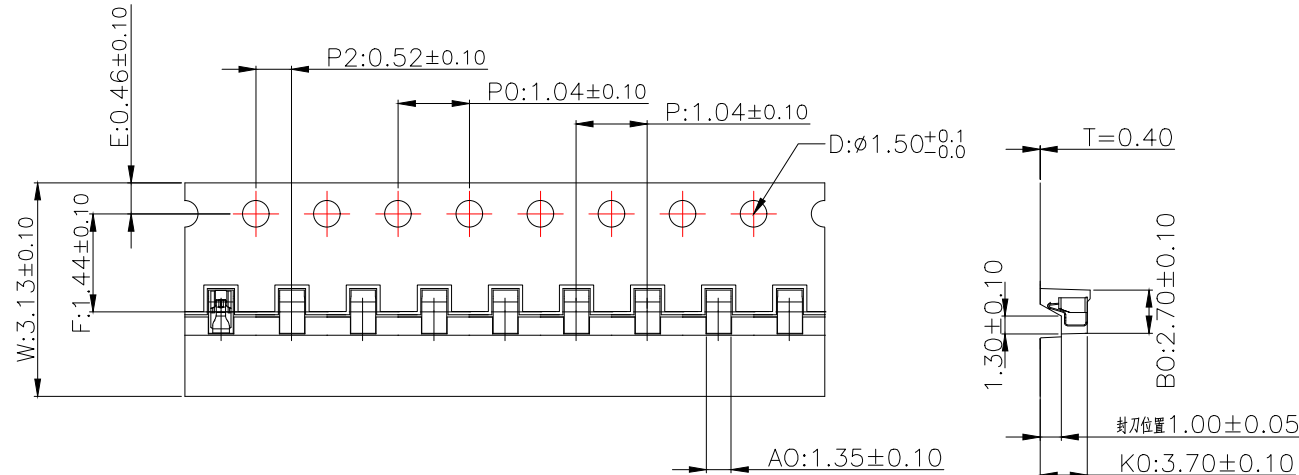
- 1:MATERIAL  
1-1: SUS-301 THICKNE=0.10MM
- 2:SPECIFICATIONS  
2-1: RATED CURRENT: 1.0A  
2-2: VOLTAGE RATING: 1.5V  
2-3: CONTACT RESISTANCE: 80mΩ/MAX  
2-4: WELDING THRUST: >3KG  
2-5: OPERATING TEMPERATURE: -40°C~+85°C
- 3:DURABILITY: 1500 CYCLES
- 4:SALT SPRAY TIME: 24H
- 5:ELECTROPLATE: THE NICKEL-PLATED SUBSTRATE IS 50u" MIN
- 6:REQUIREMENTS  
6-1:TERMINAL TO EAT FULL TIN,NOTPEELING, WELDING OBVIOUS COLOR AND OTHED ADVERSE  
6-2:ROHS, REACH, HF HALOGER ADVERSE OF DOMESTIC AND INTERNATIONAL ENVIRONMNTAL REQUIREMENTS



(For Reference Only)  
Stated At Compression

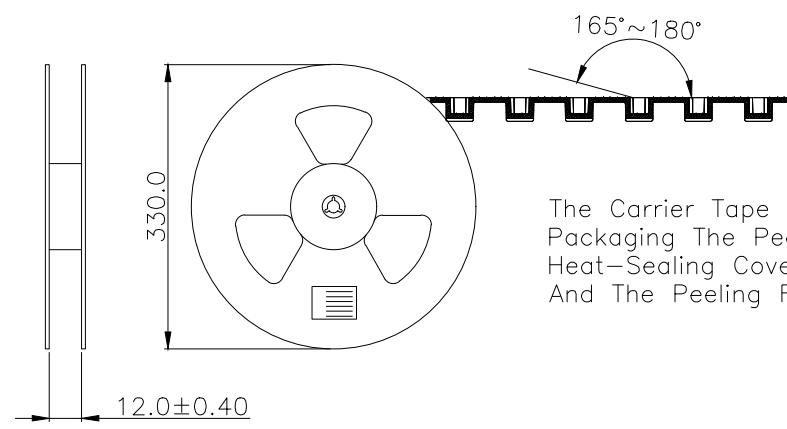
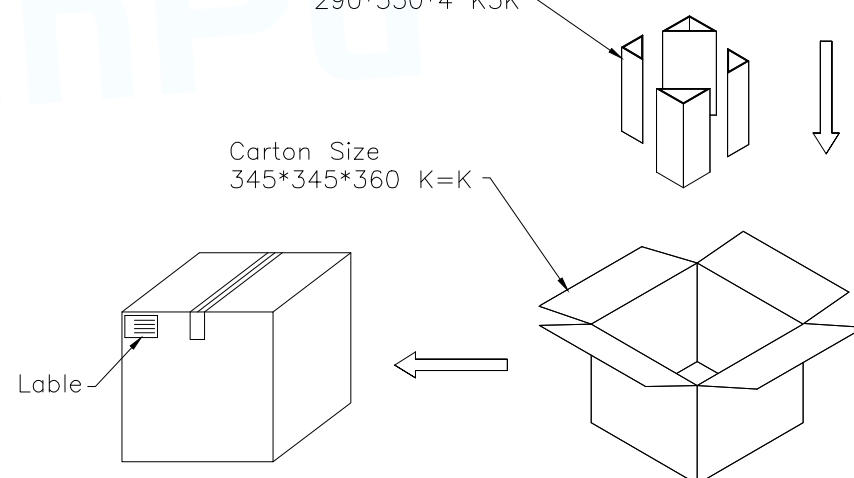


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 天线弹片 L2.55*W1.20*H3.50
			PAR ASP-D3505-B01
DECIMALS:	ANGLES:		DWN Lucas
X.:±0.30	X':±2°		CHKD Ethan
X.X:±0.20	X.X':±1°		APVD Jacob
X.XX:±0.15	X.XX':±0.5°	CUSTOMER COPY	SCALE1:1 UNIT:MM
		SIZE:A4	SHEET:1F1
			REV:A



Carton Size  
290\*330\*4 K3K

Carton Size  
345\*345\*360 K=K



The Carrier Tape Is Heat-Sealed Packaging The Peeling Angle Of The Heat-Sealing Cover Tape Is 165°~180° And The Peeling Force Is 30~120g.

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 天线弹片 L2.55*W1.20*H3.50
			PAR ASP-D3505-B01
DECIMALS:	ANGLES:		DWN Lucas
X.:±0.30	X.':±2'		CHKD Ethan
X.X:±0.20	X.X':±1'	APVD Jacob	SCALE 1:1 UNIT:MM
X.XX:±0.15	X.XX':±0.5'	CUSTOMER COPY	SIZE:A4 SHEET:1F1 REV:A

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